

In the Claims:

1. (Canceled)
2. (Currently Amended) The test structure of claim ~~[[1]]~~ 12 wherein the ~~additional structures~~ second conductive line and the third conductive line comprise dummy structures ~~without~~ that are not coupled to any circuitry function.
3. (Currently Amended) The test structure of claim ~~[[1]]~~ 12 wherein the ~~additional structures~~ second conductive line and the third conductive line comprise conductive structures that serve a circuitry function.
4. (Canceled)
5. (Canceled)
6. (Currently Amended) The test structure of claim ~~[[5]]~~ 2 wherein the dummy interconnects essentially surround the via in an equidistant manner.
7. (Currently Amended) The test structure of claim ~~[[1]]~~ 12 wherein the first, and second ~~and third conductive lines~~ interconnects and the additional structures are comprised of the same material.

8. (Original) The test structure of claim 7 wherein the first and second interconnects and the additional structures are comprised of metal.
9. (Currently Amended) The test structure of claim 8 wherein the first, and second and third conductive lines interconnects and the additional structures are comprised of aluminum.
10. (Currently Amended) The test structure of claim 8 where in the first, and second and third conductive lines interconnects and the additional structures are comprised of copper.
11. (Currently Amended) The test structure of claim 7 wherein the first, and second and third conductive lines interconnects and the additional structures are comprised of polysilicon.
12. (Original) A test structure comprising:
- a first conductive line;
 - at least one insulating layer adjacent the first conductive line;
 - a via formed in a contact hole in the at least one insulating layer, the via being electrically coupled to the first conductive line;
 - a second conductive line disposed in a plane of the first conductive line, the second conductive line extending parallel to a first edge of the first conductive line, extending around the via, and extending parallel to a second edge of the first conductive line, wherein the first edge is opposed to the second edge; and
 - a third conductive line disposed in the plane of the first conductive line, the third conductive line extending parallel to the first edge of the first conductive line, extending around

the via, and extending parallel to the second edge of the first conductive line such that the second conductive line is disposed between the first conductive line and the third conductive line.

13. (Original) The test structure of claim 12 and further comprising a fourth conductive line disposed in the plane of the first conductive line, the fourth conductive line extending parallel to the first edge of the first conductive line, extending around the via, and extending parallel to the second edge of the first conductive line such that the second and third conductive lines are disposed between the first conductive line and the fourth conductive line.

14. (Original) The test structure of claim 13 wherein the first, second, third and fourth conductive lines comprise aluminum lines.

15. (Original) The test structure of claim 13 wherein the first, second, third and fourth conductive lines comprise copper lines.

16. (Original) The test structure of claim 13 wherein the first, second, third and fourth conductive lines comprise polysilicon lines.

17. (Original) The test structure of claim 12 wherein the at least one insulating layer overlies the first conductive layer.

18. (Original) The test structure of claim 12 wherein the at least one insulating layer underlies the first conductive layer.

19. (Original) The test structure of claim 12 wherein the distance between the first edge of the first conductive line and a first edge of the second conductive line is substantially equal to the distance between a second edge of the second conductive line and an edge of the third conductive line.

20. (Original) The test structure of claim 12 and further comprising a fifth conductive line disposed in a plane that is different than the plane of the first conductive line, the fifth conductive line electrically coupled to the first conductive line through the via.

21. (New) The test structure of claim 20 wherein the fifth conductive line is disposed in a plane that is below the plane of the first conductive line.

22. (New) The test structure of claim 20 wherein the fifth conductive line is disposed in a plane that is above the plane of the first conductive line.

23. (New) The test structure of claim 2 wherein the first, second and third conductive lines are comprised of copper.